## Materials Declaration

### Molding Compound

<table>
<thead>
<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Homogeneous Material Level</th>
<th>Component Level</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
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<td>PPM</td>
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<td>Other inorganic materials</td>
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<td>9007-48-9</td>
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### Leadframe

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<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Homogeneous Material Level</th>
<th>Component Level</th>
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<tbody>
<tr>
<td>Copper &amp; its alloys</td>
<td>Copper</td>
<td>7440-50-8</td>
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### Internal Leadframe Plating

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<th>Description</th>
<th>Substance</th>
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<th>Weight (g)</th>
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<th>Component Level</th>
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<tbody>
<tr>
<td>Precious metals</td>
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### External Leadframe Plating

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### Bond Wires

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### Chip

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<tr>
<td>Other inorganic materials</td>
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### Die Attach

<table>
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### Package Totals

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ADI Proprietary
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#### Leadframe

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<th>PPM</th>
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<tr>
<td>Copper &amp; its alloys</td>
<td>Copper</td>
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<tbody>
<tr>
<td>Precious metals</td>
<td>Silver</td>
<td>7440-22-4</td>
<td>1.42 E-03</td>
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<th>Component Level</th>
<th>PPM</th>
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<tbody>
<tr>
<td>1% &amp; 6% alloys</td>
<td>Tin</td>
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#### Bond Wires

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#### Chip

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<tbody>
<tr>
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<td>Copper Oxide</td>
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<tbody>
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